

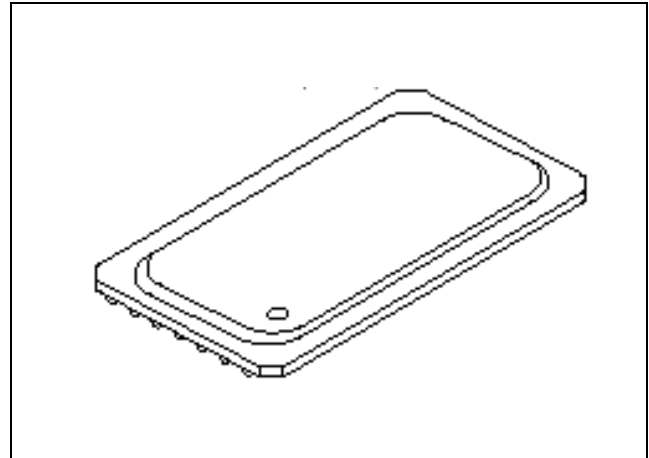
**BGA**  
**Commercial Temp**  
**Industrial Temp**

**128K x 24**  
**3Mb Asynchronous SRAM**

**8, 10, 12 ns**  
**3.3 V  $V_{DD}$**   
**Center  $V_{DD}$  and  $V_{SS}$**

**Features**

- Fast access time: 8, 10, 12 ns
- CMOS low power operation: 250/200/170 mA at minimum cycle time
- Single 3.3 V  $\pm$  0.3V power supply
- All inputs and outputs are TTL-compatible
- Fully static operation
- Industrial Temperature Option:  $-40$  to  $85^{\circ}\text{C}$
- Package
  - B: 14 mm x 22 mm, 119-bump, 1.27mm pitch BGA
  - GB: RoHS-compliant 119-bump BGA\*

**119-Bump Ball Grid Array Package**

**Description**

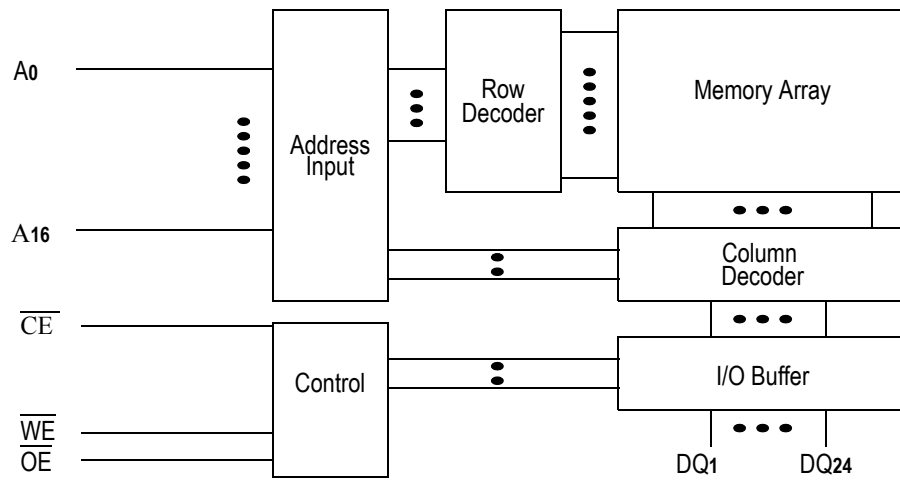
The GS73024A is a high speed CMOS Static RAM organized as 131,072 words by 24 bits. Static design eliminates the need for external clocks or timing strobes. Operating on a single 3.3 V power supply, and all inputs and outputs are TTL-compatible. The GS73024A is available in a 119-bump BGA package.

**Pin Descriptions**

Symbol	Description	Symbol	Description
A0 to A16	Address input	DQ1 to DQ24	Data input/output
WE	Write enable input	OE	Output enable input
$\overline{\text{CE}}$	Chip enable input	$V_{SS}$	Ground
$V_{DD}$	+3.3 V power supply		

\*All GSI Technology packages are at least 5/6 RoHS compliant.  
 Packages listed with the additional "G" designator are 6/6 RoHS compliant.

**Block Diagram**



## 119-Bump, 1.27 mm Pitch BGA Pad Out—Top View (Package B)

	1	2	3	4	5	6	7
A	NC	A3	A2	A16	A1	A0	NC
B	NC	A7	A6	$\overline{\text{CE}}$	A5	A4	NC
C	DQ13	NC	NC	NC	NC	NC	DQ12
D	DQ14	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>DD</sub>	DQ11
E	DQ15	NC	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>DD</sub>	NC	DQ10
F	DQ16	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>DD</sub>	DQ9
G	DQ17	NC	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>DD</sub>	NC	DQ8
H	DQ18	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>DD</sub>	DQ7
J	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>DD</sub>
K	DQ19	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>DD</sub>	DQ6
L	DQ20	NC	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>DD</sub>	NC	DQ5
M	DQ21	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>DD</sub>	DQ4
N	DQ22	NC	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>DD</sub>	NC	DQ3
P	DQ23	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>DD</sub>	DQ2
R	DQ24	NC	NC	NC	NC	NC	DQ1
T	NC	A11	A10	$\overline{\text{WE}}$	A9	A8	NC
U	NC	A15	A14	$\overline{\text{OE}}$	A13	A12	NC

**Truth Table**

$\overline{\text{CE}}$	$\overline{\text{OE}}$	$\overline{\text{WE}}$	Mode	DQ0 to DQ23	$V_{\text{DD}}$ Current
H	X	X	Not selected	High Z	ISB1, ISB2
L	L	H	Read	Data Out	$I_{\text{DD}}$
L	X	L	Write	Data In	
L	H	H	Output disable	High Z	

X: "H" or "L"

**Absolute Maximum Ratings**

Parameter	Symbol	Rating	Unit
Supply Voltage	$V_{\text{DD}}$	-0.5 to +4.6	V
Input Voltage	$V_{\text{IN}}$	-0.5 to $V_{\text{DD}} + 0.5$ ( $\leq 4.6$ V max.)	V
Output Voltage	$V_{\text{OUT}}$	-0.5 to $V_{\text{DD}} + 0.5$ ( $\leq 4.6$ V max.)	V
Allowable BGA power dissipation	PD	1.5	W
Storage temperature	$T_{\text{STG}}$	-55 to 150	$^{\circ}\text{C}$

**Note:**

Permanent device damage may occur if Absolute Maximum Ratings are exceeded. Functional operation shall be restricted to Recommended Operating Conditions. Exposure to higher than recommended voltages for extended periods of time could affect device reliability.

**Recommended Operating Conditions**

Parameter	Symbol	Min	Typ	Max	Unit
Supply Voltage for -10/12	$V_{DD}$	3.0	3.3	3.6	V
Supply Voltage for -8	$V_{DD}$	3.135	3.3	3.6	V
Input High Voltage	$V_{IH}$	2.0	—	$V_{DD}+0.3$	V
Input Low Voltage	$V_{IL}$	-0.3	—	0.8	V
Ambient Temperature, Commercial Range	$T_{Ac}$	0	—	70	°C
Ambient Temperature, Industrial Range	$T_{Ai}$	-40	—	85	°C

**Notes:**

1. Input overshoot voltage should be less than  $V_{DD} + 2\text{ V}$  and not exceed 20 ns.
2. Input undershoot voltage should be greater than  $-2\text{ V}$  and not exceed 20 ns.

**Capacitance**

Parameter	Symbol	Test Condition	Max	Unit
Input Capacitance	$C_{IN}$	$V_{IN} = 0\text{ V}$	5	pF
I/O Capacitance	$C_{OUT}$	$V_{OUT} = 0\text{ V}$	7	pF

**Notes:**

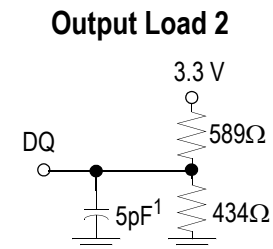
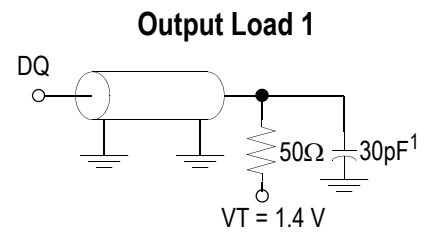
1. Tested at  $T_A = 25^\circ\text{C}$ ,  $f = 1\text{ MHz}$
2. These parameters are sampled and are not 100% tested.

**DC I/O Pin Characteristics**

Parameter	Symbol	Test Conditions	Min	Max
Input Leakage Current	$I_{IL}$	$V_{IN} = 0\text{ to }V_{DD}$	-1 $\mu\text{A}$	1 $\mu\text{A}$
Output Leakage Current	$I_{OL}$	Output High Z, $V_{OUT} = 0\text{ to }V_{DD}$	-1 $\mu\text{A}$	1 $\mu\text{A}$
Output High Voltage	$V_{OH}$	$I_{OH} = -4\text{ mA}$	2.4	—
Output Low Voltage	$V_{OL}$	$I_{OL} = +4\text{ mA}$	—	0.4 V

**AC Test Conditions**

Parameter	Conditions
Input high level	$V_{IH} = 2.4\text{ V}$
Input low level	$V_{IL} = 0.4\text{ V}$
Input rise time	$t = 1\text{ V/ns}$
Input fall time	$t_f = 1\text{ V/ns}$
Input reference level	1.4 V
Output reference level	1.4 V
Output load	<b>Fig. 1 &amp; 2</b>


**Notes:**

1. Includes scope and jig capacitance
2. Test conditions as specified with output loading as shown in Fig. 1 unless otherwise noted
3. Output load 2 for  $t_{LZ}$ ,  $t_{HZ}$ ,  $t_{OLZ}$  and  $t_{OHZ}$

**Power Supply Currents**

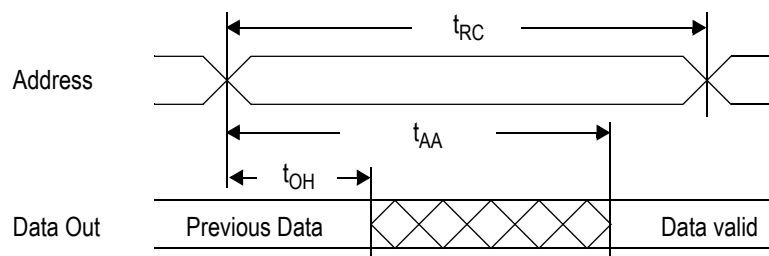
Parameter	Symbol	Test Conditions	0 to 70°C			-40 to 85°C		
			8 ns	10 ns	12 ns	8 ns	10 ns	12 ns
Operating Supply Current	$I_{DD}$	$\overline{CE} \leq V_{IL}$ All other inputs $\geq V_{IH}$ or $\leq V_{IL}$ Min. cycle time $I_{OUT} = 0\text{ mA}$	250 mA	200 mA	170 mA	260 mA	210 mA	180 mA
Standby Current	$I_{SB1}$	$\overline{CE} \geq V_{IH}$ All other inputs $\geq V_{IH}$ or $\leq V_{IL}$ Min. cycle time	40 mA	40 mA	30 mA	50 mA	50 mA	40 mA
Standby Current	$I_{SB2}$	$CE \geq V_{DD} - 0.2\text{V}$ All other inputs $\geq V_{DD} - 0.2\text{V}$ or $\leq 0.2\text{V}$	10 mA			20 mA		

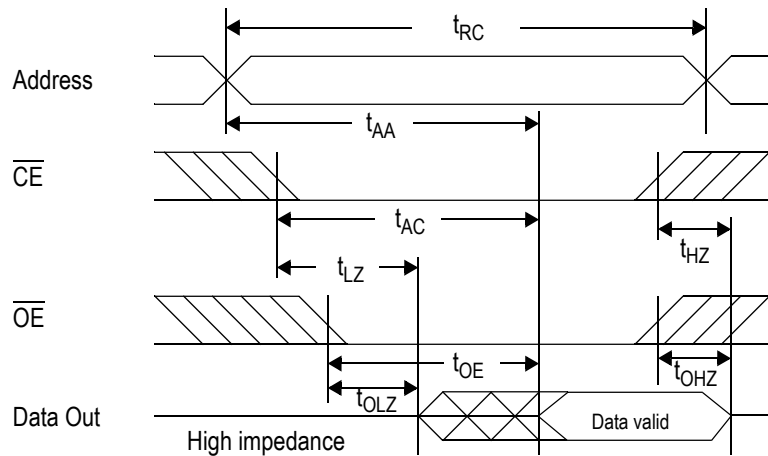
**AC Characteristics**
**Read Cycle**

Parameter	Symbol	-8		-10		-12		Unit
		Min	Max	Min	Max	Min	Max	
Read cycle time	$t_{RC}$	8	—	10	—	12	—	ns
Address access time	$t_{AA}$	—	8	—	10	—	12	ns
Chip enable access time ( $\overline{CE}$ )	$t_{AC}$	—	8	—	10	—	12	ns
MUX control to output valid ( $V/\overline{S}$ )	$t_{AV}$	—	8	—	10	—	12	ns
Output enable to output valid ( $\overline{OE}$ )	$t_{OE}$	—	4	—	5	—	6	ns
Output hold from address change	$t_{OH}$	3	—	3	—	3	—	ns
Output hold from MUX controls change	$t_{OH1}$	3	—	3	—	3	—	ns
Chip enable to output in low Z ( $\overline{CE}$ )	$t_{LZ}^*$	3	—	3	—	3	—	ns
Output enable to output in low Z ( $\overline{OE}$ )	$t_{OLZ}^*$	0	—	0	—	0	—	ns
Chip disable to output in High Z ( $\overline{CE}$ )	$t_{HZ}^*$	—	4	—	5	—	6	ns
Output disable to output in High Z ( $\overline{OE}$ )	$t_{OHZ}^*$	—	4	—	5	—	6	ns

\* These parameters are sampled and are not 100% tested

**Read Cycle 1:  $\overline{CE} = \overline{OE} = V_{IL}$ ,  $\overline{WE} = V_{IH}$**



**Read Cycle 2:  $\overline{WE} = V_{IH}$** 

**Write Cycle**

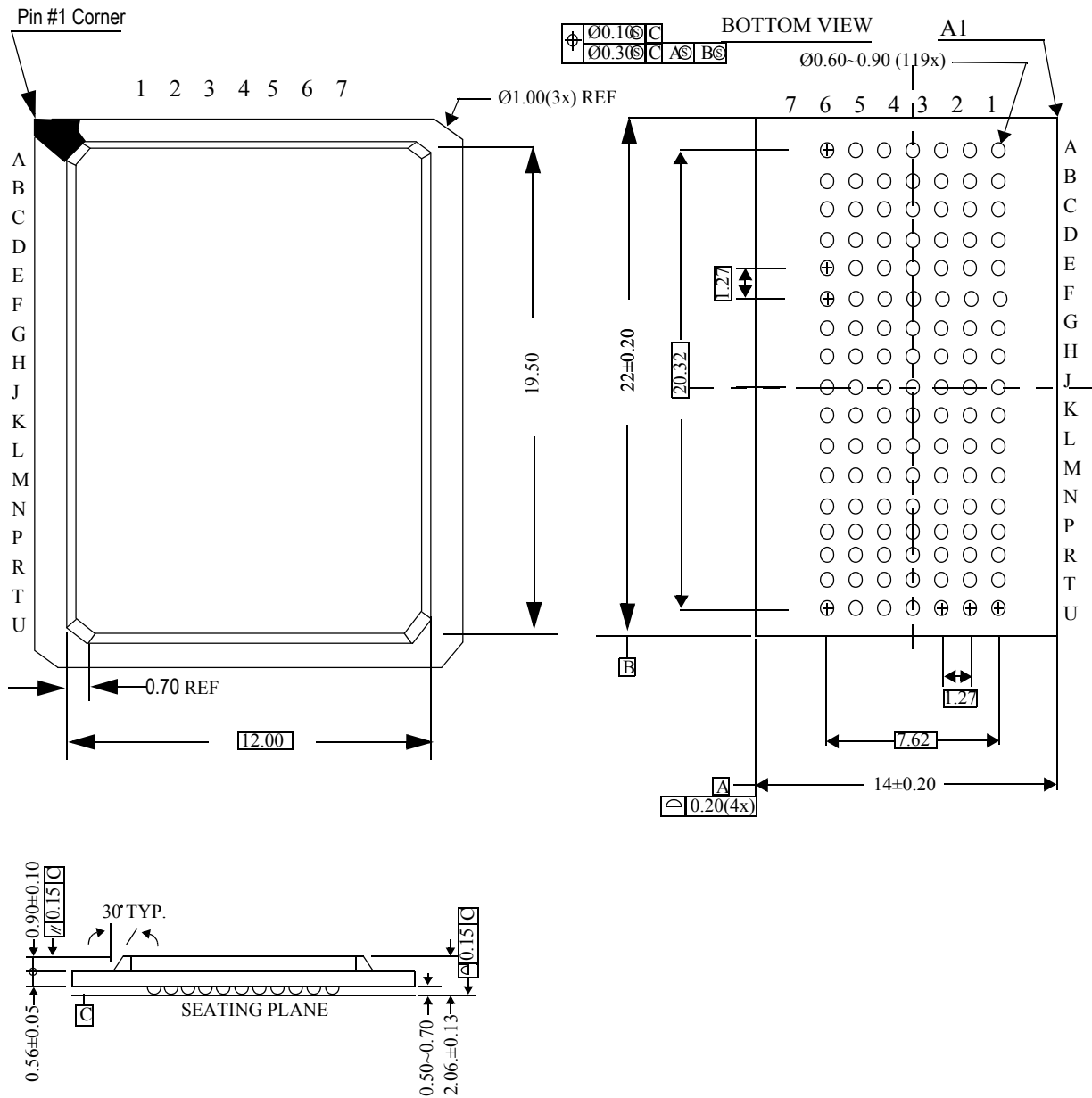
Parameter	Symbol	-8		-10		-12		Unit
		Min	Max	Min	Max	Min	Max	
Write cycle time	$t_{WC}$	8	—	10	—	12	—	ns
Address valid to end of write	$t_{AW}$	5.5	—	7	—	8	—	ns
Chip enable to end of write ( $\overline{CE}$ )	$t_{CW}$	5.5	—	7	—	8	—	ns
Data set up time	$t_{DW}$	4	—	5	—	6	—	ns
Data hold time	$t_{DH}$	0	—	0	—	0	—	ns
Write pulse width	$t_{WP}$	5.5	—	7	—	8	—	ns
Address set up time	$t_{AS}$	0	—	0	—	0	—	ns
Write recovery time ( $\overline{WE}$ )	$t_{WR}$	0	—	0	—	0	—	ns
Write recovery time ( $\overline{CE}$ )	$t_{WR1}$	0	—	0	—	0	—	ns
Output Low Z from end of write	$t_{WLZ}^*$	2	—	3	—	3	—	ns
Write to output in High Z	$t_{WHZ}^*$	—	4	—	5	—	6	ns

\* These parameters are sampled and are not 100% tested

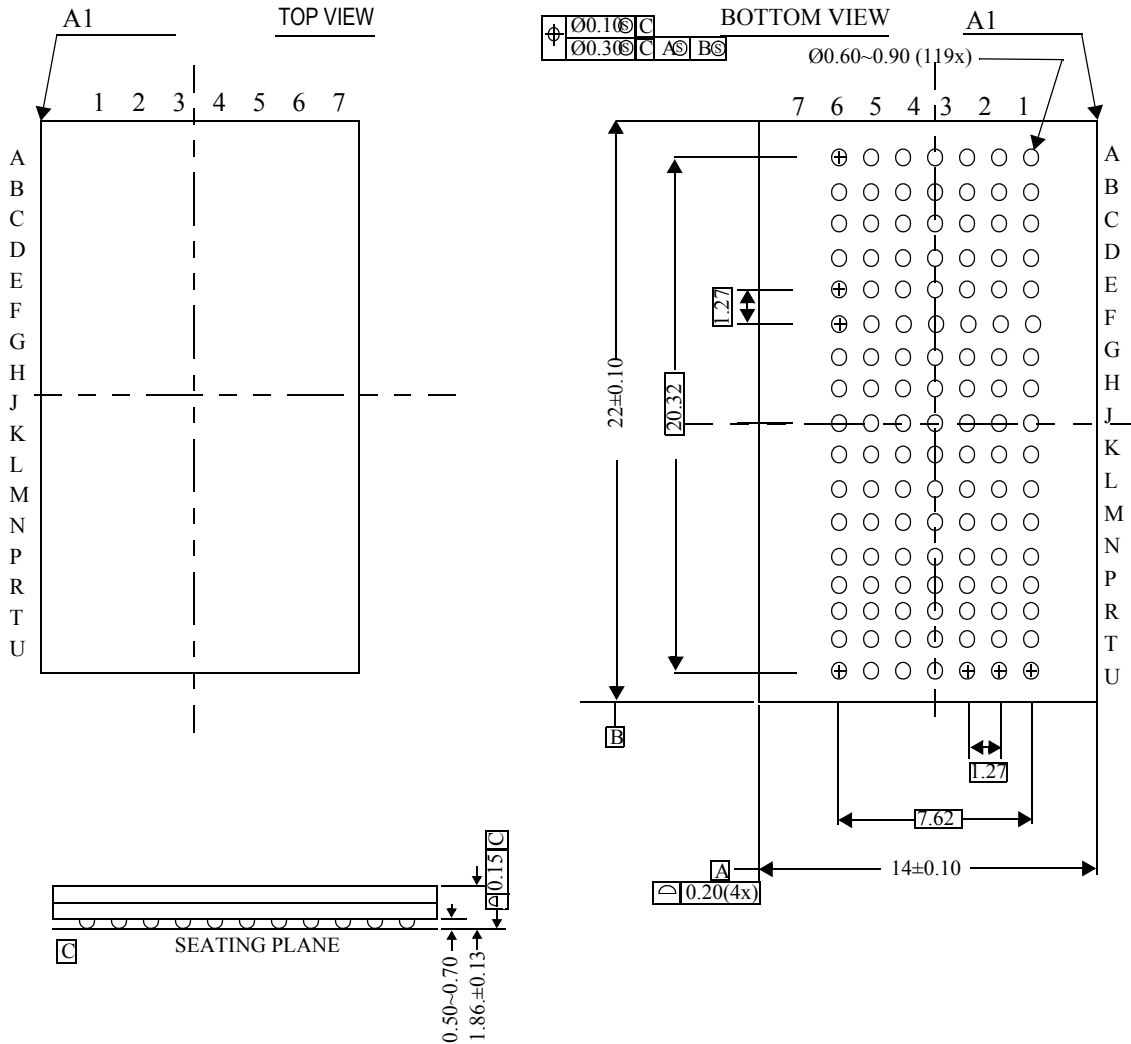




**Package Dimensions—119-Bump FPBGA (Package B, Variation 1)**  
**(Date Code: yyww.31)**



**Package Dimensions—119-Bump FPBGA (Package B, Variation 2)**  
**(Date Code: yyww.3H)**



**Ordering Information**

Part Number <sup>1</sup>	Package <sup>2</sup>	Access Time	Temp. Range	Status
GS73024AB-8	119-Bump BGA <sup>3</sup>	8 ns	Commercial	MP
GS73024AB-10	119-Bump BGA <sup>3</sup>	10 ns	Commercial	MP
GS73024AB-12	119-Bump BGA <sup>3</sup>	12 ns	Commercial	MP
GS73024AB-8I	119-Bump BGA <sup>3</sup>	8 ns	Industrial	MP
GS73024AB-10I	119-Bump BGA <sup>3</sup>	10 ns	Industrial	MP
GS73024AB-12I	119-Bump BGA <sup>3</sup>	12 ns	Industrial	MP
GS73024AGB-8	RoHS-compliant 119-Bump BGA <sup>3</sup>	8 ns	Commercial	PQ
GS73024AGB-10	RoHS-compliant 119-Bump BGA <sup>3</sup>	10 ns	Commercial	PQ
GS73024AGB-12	RoHS-compliant 119-Bump BGA <sup>3</sup>	12 ns	Commercial	PQ
GS73024AGB-8I	RoHS-compliant 119-Bump BGA <sup>3</sup>	8 ns	Industrial	PQ
GS73024AGB-10I	RoHS-compliant 119-Bump BGA <sup>3</sup>	10 ns	Industrial	PQ
GS73024AGB-12I	RoHS-compliant 119-Bump BGA <sup>3</sup>	12 ns	Industrial	PQ

**Notes:**

1. Customers requiring Tape and Reel should add the character "T" to the end of the part number. For example: GS73024AB-12T.
2. All GSI Technology packages are at least 5/6 RoHS compliant. Packages listed with the additional "G" designator are 6/6 RoHS compliant.
3. Please see pages 9 and 10 for date code information for Variation 1 and Variation 2 of the 119-bump BGA.

**Revision History**

Rev. Code: Old; New	Types of Changes Format or Content	Page/Revisions/Reason
GS73024A_r1		• Creation of new datasheet
GS73024A_r1; GS73024A_r1_01	Content	<ul style="list-style-type: none"> <li>• Corrected pinout (balls C3, C5, R2, R3, R5, R6 changed to NC)</li> <li>• Corrected pin description table to reflect pinout corrections</li> <li>• Corrected truth table to reflect pinout corrections</li> </ul>
GS73024A_r1_01; GS73024A_r1_02	Content/Format	<ul style="list-style-type: none"> <li>• Updated format</li> <li>• Added variation information to package mechanical</li> </ul>
GS73024A_r1_02; GS73024A_r1_03	Content	<ul style="list-style-type: none"> <li>• Added Variation 2 119 BGA to datasheet</li> <li>• Added date codes to mechanicals</li> </ul>
GS73024A_r1_03; GS73024A_r1_04	Content	<ul style="list-style-type: none"> <li>• Added RoHS-compliant package information</li> <li>• Added RoHS-compliant disclaimers</li> </ul>